

M5M41000BP,J,L,VP,RV-7,-8,-10

FAST PAGE MODE 1048576-BIT(1048576-WORD BY 1-BIT)DYNAMIC RAM

DESCRIPTION

This is a family of 1048576-word by 1-bit dynamic RAMs, fabricated with the high performance CMOS process, and is ideal for large-capacity memory systems where high speed, low power dissipation, and low costs are essential. The use of triple-layer polysilicon process combined with silicide technology and a single-transistor dynamic storage cell provide high circuit density at reduced costs, and the use of dynamic circuitry including sense amplifiers assures low power dissipation. Multiplexed address inputs permit both a reduction in pins and an increase in system densities.

In addition to the RAS-only refresh mode, the hidden refresh mode and CAS before RAS refresh mode are available.

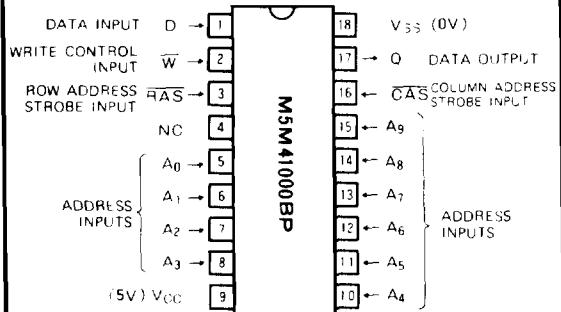
FEATURES

Type name	RAS access time (max ns)	CAS access time (max ns)	Address access time (max ns)	Cycle time (min ns)	Power dissipation (typ mW)
M5M41000B-7	70	20	35	140	230
M5M41000B-8	80	20	40	160	200
M5M41000B-10	100	25	50	190	175

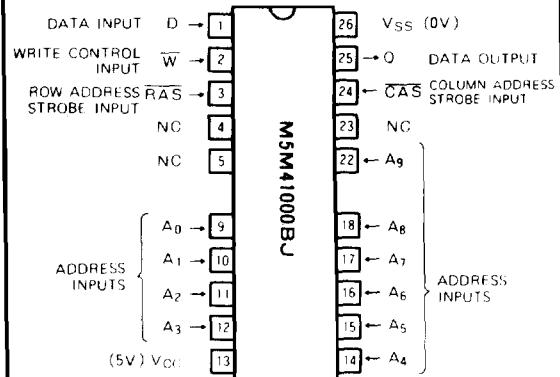
APPLICATION

Main memory unit for computers, Microcomputer memory, Refresh memory for CRT

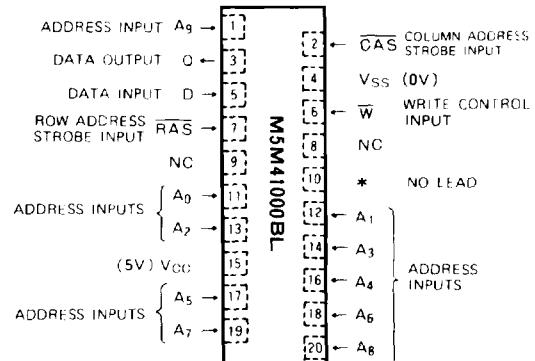
PIN CONFIGURATION (TOP VIEW)



Outline 18P4Y (DIP)



Outline 26POJ (SOJ)

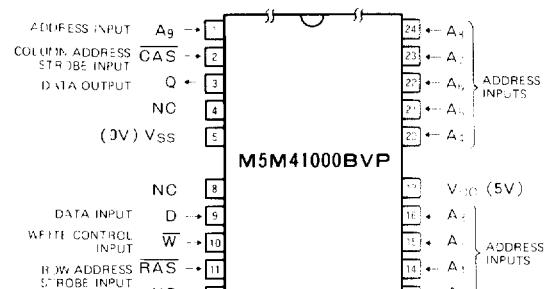


Outline 20P5L-A(ZIP)

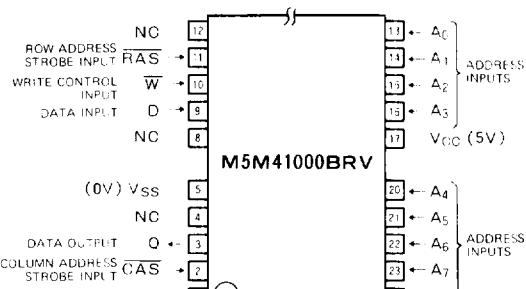
NC: NO CONNECTION

FAST PAGE MODE 1048576-BIT(1048576-WORD BY 1-BIT)DYNAMIC RAM

PIN CONFIGURATION (TOP VIEW)



Outline 24P3B-L (TSOP)



Outline 24P3B-M (TSOP)

NC NO CONNECTION

FUNCTION

The M5M41000BP, J, L, VP, RV provide, in addition to normal read, write, and read-modify-write operations, a

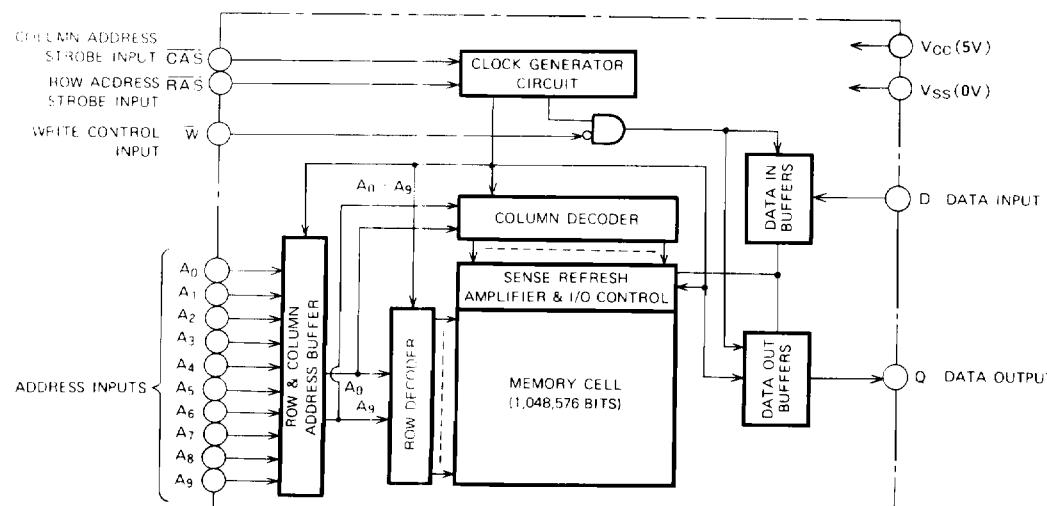
number of other functions, e.g., fast page mode, RAS-only refresh, and delayed-write. The input conditions for each are shown in Table 1.

Table 1 Input conditions for each mode

Operation	Inputs						Output	Refresh	Remark
	RAS	CAS	W	D	Row address	Column address			
Read	ACT	ACT	NAC	DNC	APD	APD	VLD	YES	
Write (Early write)	ACT	ACT	ACT	VLD	APD	APD	OPN	YES	
Read Modify write	ACT	ACT	ACT	VLD	APD	APD	VLD	YES	
RAS-only refresh	ACT	NAC	DNC	DNC	APD	DNC	OPN	YES	
Hidden refresh	ACT	ACT	DNC	DNC	DNC	DNC	VLD	YES	
CAS-before RAS refresh	ACT	ACT	DNC	DNC	DNC	DNC	OPN	YES	
Standby	NAC	DNC	DNC	DNC	DNC	DNC	OPN	NO	

Note ACT active, NAC inactive, DNC don't care, VLD valid, APD applied, OPN open

BLOCK DIAGRAM



M5M41000BP, J, L, VP, RV-7, -8, -10**FAST PAGE MODE 1048576-BIT(1048576-WORD BY 1-BIT)DYNAMIC RAM****ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Conditions	Ratings	Unit
V _{CC}	Supply voltage		-1 ~ 7	V
V _I	Input voltage	With respect to V _{SS}	-1 ~ 7	V
V _O	Output voltage		-1 ~ 7	V
I _O	Output current		50	mA
P _d	Power dissipation	T _a = 25°C	1000	mW
T _{opr}	Operating temperature		0 ~ 70	°C
T _{stg}	Storage temperature		65 ~ 150	°C

RECOMMENDED OPERATING CONDITIONS (T_a = 0 ~ 70°C, V_{CC} = 5V ± 10%, V_{SS} = 0V, unless otherwise noted) (Note 1)

Symbol	Parameter	Limits			Unit
		Min	Nom	Max	
V _{CC}	Supply voltage	4.5	5	5.5	V
V _{SS}	Supply voltage	0	0	0	V
V _{IH}	High-level input voltage, all inputs	2.4		6.5	V
V _{IL}	Low-level input voltage, all inputs	-1.0		0.8	V

Note 1 All voltage values are with respect to V_{SS}**ELECTRICAL CHARACTERISTICS (T_a = 0 ~ 70°C, V_{CC} = 5V ± 10%, V_{SS} = 0V, unless otherwise noted) (Note 2)**

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
V _{DH}	High-level output voltage	I _{OH} = 5mA	2.4		V _{CC}	V
V _{OL}	Low-level output voltage	I _{OL} = 4.2mA	0		0.4	V
I _{OZ}	Off state output current	Q floating, 0V ≤ V _{OL} ≤ 5.5V	10		10	mA
I _{IN}	Input current	0V ≤ V _{IN} ≤ 6.5V, Other input pins 0V	10		10	mA
I _{CC1(AV)}	Average supply current from V _{CC} operating (Note 3, 4)	M5M41000B-7			80	
		M5M41000B-8			70	
		M5M41000B-10			60	
I _{CC2(AV)}	Average supply current from V _{CC} , stand-by (Note 6)	RAS, CAS cycling				
		t _{RC} = t _{WC} = min, output open				
I _{CC3(AV)}	Average supply current from V _{CC} refreshing (Note 3)	RAS cycling, CAS, V _{IH}			80	
		I _{RC} = min, output open			70	
		M5M41000B-7			60	
I _{CC4(AV)}	Average supply current from V _{CC} Fast page mode (Note 3, 4)	M5M41000B-8				
		M5M41000B-10				
		M5M41000B-7			70	
I _{CC6(AV)}	Average supply current from V _{CC} CAS before RAS refresh mode (Note 3)	M5M41000B-8			60	
		M5M41000B-10			50	
		M5M41000B-7	CAS before RAS refresh cycling		80	
		M5M41000B-8	t _{RC} = min, output open		70	
		M5M41000B-10			60	

Note 2 Current flowing into an IC is positive, out is negative.

3. I_{CC1(AV)}, I_{CC3(AV)}, I_{CC4(AV)} and I_{CC6(AV)} are dependent on cycle rate. Maximum current is measured at the fastest cycle rate.4. I_{CC1(AV)} and I_{CC4(AV)} are dependent on input loading. Specified values are obtained with the output open.**CAPACITANCE (T_a = 0 ~ 70°C, V_{CC} = 5V ± 10%, V_{SS} = 0V, unless otherwise noted)**

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
C _(A)	Input capacitance, address inputs (Note 5)	V _I = V _{SS} , f = 1MHz, V _I = 25mVrms			5	pF
C _(D)	Input capacitance, data input				5	pF
C _(W)	Input capacitance, write control input	f = 1MHz			7	pF
C _(RAS)	Input capacitance, RAS input	V _I = 25mVrms			7	pF
C _(CAS)	Input capacitance, CAS input				7	pF
C _O	Output capacitance	V _O = V _{SS} , f = 1MHz, V _I = 25mVrms			7	pF

Note 5 C_(A) of ZIP is 6pF (max).

M5M41000BP, J, L, VP, RV-7, -8, -10**FAST PAGE MODE 1048576-BIT(1048576-WORD BY 1-BIT)DYNAMIC RAM****SWITCHING CHARACTERISTICS ($T_a = 0 \sim 70^\circ C$, $V_{CC} = 5V \pm 10\%$, $V_{SS} = 0V$, unless otherwise noted) (Note 6)**

Symbol	Parameter	Limits						Unit	
		M5M41000B-7		M5M41000B-8		M5M41000B-10			
		Min	Max	Min	Max	Min	Max		
t_{CAC}	Access time from \overline{CAS}	(Note 7, 8)		20		20		25 ns	
t_{RAC}	Access time from \overline{RAS}	(Note 7, 9)		70		80		100 ns	
t_{CAA}	Column address access time	(Note 7, 10)		35		40		50 ns	
t_{CPA}	Access time from \overline{CAS} precharge	(Note 7, 11)		40		45		55 ns	
t_{CLZ}	Output low impedance time from \overline{CAS} low	(Note 7)	5		5		5	ns	
t_{OFF}	Output disable time after \overline{CAS} high	(Note 12)	0	20	0	20	0	25 ns	

Note 6: An initial pause of 500μs is required after power-up followed by any 8 RAS or RAS/ \overline{CAS} cycles before proper device operation is achieved.

Note that RAS may be cycled during the initial pause. And any 8 RAS or RAS/ \overline{CAS} cycles are required after prolonged periods of RAS inactivity before proper device operation is achieved.

7: Measured with a load circuit equivalent to 2TTT loads and 10pF.

8: Assume that $t_{RCD(max)} \leq t_{RCD}$ and $t_{ASC} \geq t_{ASC(max)}$.

9: Assumes that $t_{RCD} \leq t_{RCD(max)}$ and $t_{RAD} \leq t_{RAD(max)}$. If t_{RCD} or t_{RAD} is greater than the maximum recommended value shown in this table, t_{RAC} will increase by amount that t_{RCD} or t_{RAD} exceeds the value shown.

10: Assume that $t_{RAD} \geq t_{RAD(max)}$ and $t_{ASC} \leq t_{ASC(max)}$.

11: Assume that $t_{CP} \leq t_{CP(max)}$ and $t_{ASC} \geq t_{ASC(max)}$.

12: $t_{OFF(max)}$ defines the time at which the output achieves the high impedance state ($|I_{OUT}| \leq |\pm 10\mu A|$) and is not reference to $V_{OH(min)}$ or $V_{OL(max)}$.

TIMING REQUIREMENTS (For Read, Write, Read-Modify-Write, Refresh, and Fast-Page Mode Cycles)

($T_a = 0 \sim 70^\circ C$, $V_{CC} = 5V \pm 10\%$, $V_{SS} = 0V$, unless otherwise noted, see notes 13, 14)

Symbol	Parameter	Limits						Unit	
		M5M41000B-7		M5M41000B-8		M5M41000B-10			
		Min	Max	Min	Max	Min	Max		
t_{REF}	Refresh cycle time			8		8		8 ms	
t_{RP}	RAS high pulse width		60		70		80	ns	
t_{RCD}	Delay time, \overline{RAS} low to \overline{CAS} low	(Note 15)	20	50	25	60	25	75 ns	
t_{RCR}	Delay time, \overline{CAS} high to \overline{RAS} low	(Note 16)	10		10		10	ns	
t_{CPW}	\overline{CAS} high pulse width		10		10		10	ns	
t_{RAD}	Column address delay time from \overline{RAS} low	(Note 17)	15	35	20	40	20	50 ns	
t_{ASB}	Row address setup time before \overline{RAS} low		0		0		0	ns	
t_{ASD}	Column address setup time before \overline{CAS} low	(Note 18)	0	10	0	15	0	20 ns	
t_{RAH}	Row address hold time after \overline{RAS} low		10		15		15	ns	
t_{CAH}	Column address hold time after \overline{CAS} low		15		20		20	ns	
t_T	Transition time	(Note 19)	3	50	3	50	3	50 ns	

Note 13: The timing requirements are assumed $t_F = 5ns$

14: $V_{IH(min)}$ and $V_{IL(max)}$ are reference levels for measuring timing of input signals.

15: $t_{RCD(max)}$ is specified as a reference point only. If t_{RCD} is less than $t_{RCD(max)}$, access time is t_{RAC} . If t_{RCD} is greater than $t_{RCD(max)}$, access time is defined as t_{CAC} and t_{CAA} as shown in notes 8, 10.

16: t_{CP} requirement is applicable for all RAS/ \overline{CAS} cycles.

17: $t_{RAD(max)}$ is specified as a reference point only. If $t_{RAD} \geq t_{RAD(max)}$ and $t_{ASC} \leq t_{ASC(max)}$, access time is controlled exclusively by t_{CAA} .

18: $t_{ASC(max)}$ is specified as a reference point only. If $t_{RCD} \geq t_{RCD(max)}$ and $t_{ASC} \geq t_{ASC(max)}$, access time is controlled exclusively by t_{CAC} .

19: t_F is measured between $V_{IH(min)}$ and $V_{IL(max)}$.

FAST PAGE MODE 1048576-BIT(1048576-WORD BY 1-BIT)DYNAMIC RAM**Read and Refresh Cycles**

Symbol	Parameter	Limits						Unit
		M5M41000B-7		M5M41000B-8		M5M41000B-10		
Min	Max	Min	Max	Min	Max	Min	Max	
t _{RC}	Read cycle time	140		160		190		ns
t _{RAS}	RAS low pulse width	70	10000	80	10000	100	10000	ns
t _{CAS}	CAS low pulse width	20	10000	20	10000	25	10000	ns
t _{CSH}	CAS hold time after RAS low	70		80		100		ns
t _{RSH}	RAS hold time after CAS low	20		20		25		ns
t _{ACS}	Read setup time before CAS low	0		0		0		ns
t _{RCH}	Read hold time after CAS high	(Note 20)	0		0		0	ns
t _{RHH}	Read hold time after RAS high	(Note 20)	10		10		10	ns
t _{CAI}	Column address to RAS setup time	35		40		50		ns
t _{APC}	Precharge to CAS active time	0		0		0		ns

Note 20 Either t_{RCH} or t_{RHH} must be satisfied for a read cycle.**Write Cycle (Early Write and Delayed Write)**

Symbol	Parameter	Limits						Unit
		M5M41000B-7		M5M41000B-8		M5M41000B-10		
Min	Max	Min	Max	Min	Max	Min	Max	
t _{WC}	Write cycle time	140		160		190		ns
t _{RAS}	RAS low pulse width	70	10000	80	10000	100	10000	ns
t _{CAS}	CAS low pulse width	20	10000	20	10000	25	10000	ns
t _{CSH}	CAS hold time after RAS low	70		80		100		ns
t _{RSH}	RAS hold time after CAS low	20		20		25		ns
t _{WCS}	Write setup time before CAS low	(Note 23)	0		0		0	ns
t _{WCH}	Write hold time after CAS low		15		15		20	ns
t _{WP}	Write pulse width		15		15		20	ns
t _{DS}	Data setup time		0		0		0	ns
t _{DH}	Data hold time after CAS low		15		15		20	ns

M5M41000BP, J, L, VP, RV-7, -8, -10**FAST PAGE MODE 1048576-BIT(1048576-WORD BY 1-BIT)DYNAMIC RAM****Read-Write and Read-Modify-Write Cycles**

Symbol	Parameter	Limits						Unit	
		M5M41000B-7		M5M41000B-8		M5M41000B-10			
		Min	Max	Min	Max	Min	Max		
t _{RWC}	Read-Write cycle time (Note 21)	165		185		220		ns	
t _{RMWC}	Read-Modify-Write cycle time (Note 22)	165		185		220		ns	
t _{RAS}	RAS low pulse width	95	10000	105	10000	130	10000	ns	
t _{CAS}	CAS low pulse width	45	10000	45	10000	55	10000	ns	
t _{CHS}	CAS hold time after RAS low	95		105		130		ns	
t _{CSH}	RAS hold time after CAS low	45		45		55		ns	
t _{RS}	Read setup time before CAS low	0		0		0		ns	
t _{CWD}	Delay time, CAS low to write low (Note 23)	20		20		25		ns	
t _{RWD}	Delay time, RAS low to write low (Note 23)	70		80		100		ns	
t _{CWD}	CAS hold time after write low	20		20		25		ns	
t _{RWD}	RAS hold time after write low	20		20		25		ns	
t _{WD}	Write pulse width	15		15		20		ns	
t _{DS}	Data setup time	0		0		0		ns	
t _{DH}	Data hold time after write low	15		15		20		ns	
t _{AWD}	Delay time, address to write low (Note 23)	35		40		50		ns	

Note 21: t_{RWC} is specified as t_{RWC(min)} = t_{RCD(max)} + t_{CWD(max)} + t_{RWL(max)} + t_{RPI(max)} + 3t_T.Note 22: t_{RMWC} is specified as t_{RMWC(min)} = t_{RCAC(max)} + t_{RWL(max)} + t_{RPI(max)} + 3t_T.

Note 23: t_{CWD}, t_{RWD}, t_{CWD}, and t_{AWD} do not define the limits of operation, but are included as electrical characteristics only.
When t_{WC5} ≥ t_{WC5(min)}, an early write cycle is performed, and the data output keeps the high-impedance state. When t_{RWD} ≥ t_{RWD(min)}, t_{CWD} ≥ t_{CWD(min)} and t_{AWD} ≥ t_{AWD(min)}, a read-write cycle is performed, and the data of the selected address will be read out on the data output. If neither of the above condition is satisfied, the condition of Q (at access time and until C_S goes back to V_{IH}) is indeterminate.

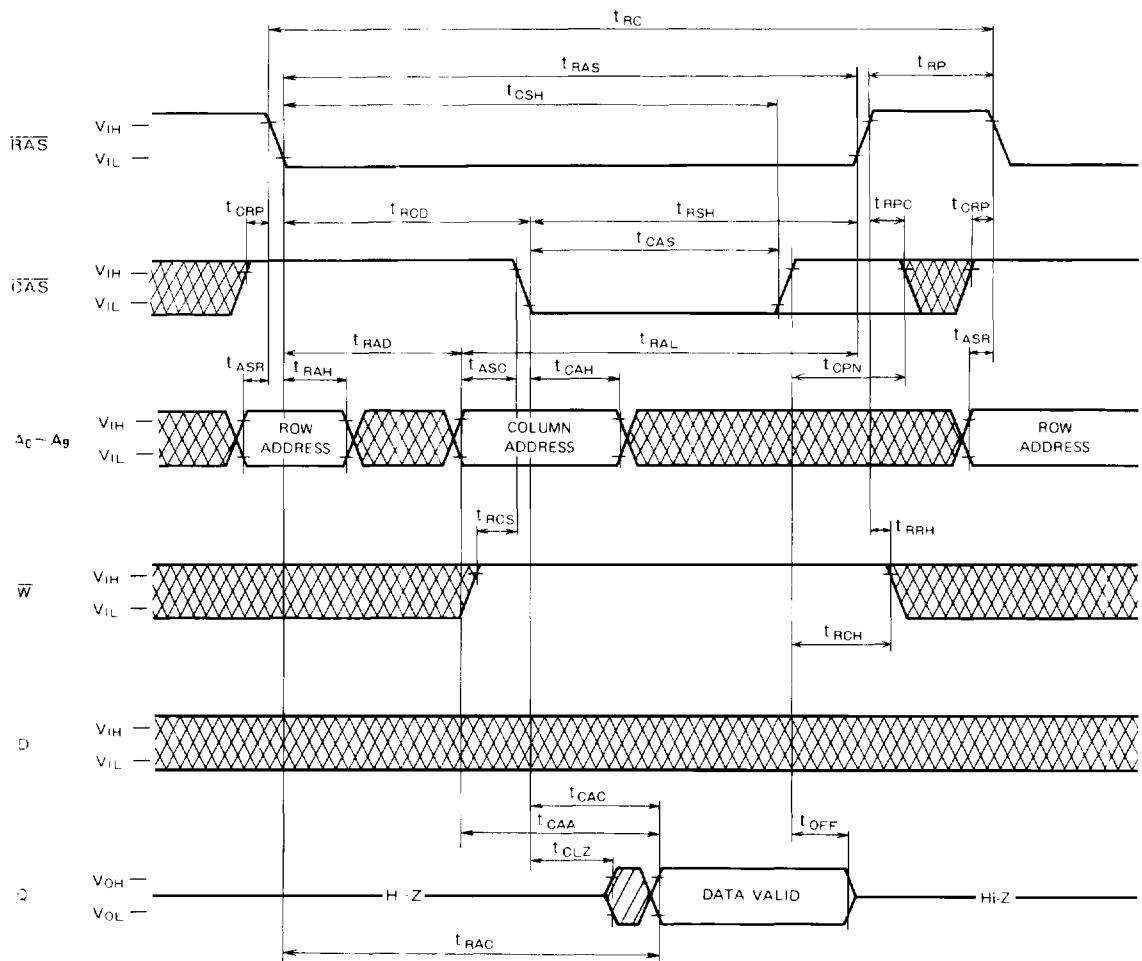
Fast Page Mode Cycle (Read, Early Write, Read-Write, Read-Modify-Write Cycles)

Symbol	Parameter	Limits						Unit	
		M5M41000B-7		M5M41000B-8		M5M41000B-10			
		Min	Max	Min	Max	Min	Max		
t _{PPC}	Fast Page mode cycle time	45		50		60		ns	
t _{RWP}	Fast Page mode R/W, R/M/W cycle time	70		75		90		ns	
t _{RAS}	RAS low pulse width for read, write cycle	115	100000	130	100000	160	100000	ns	
t _{CAS}	CAS low pulse width for read cycle	20	10000	20	10000	25	10000	ns	
t _{CP}	CAS high pulse width (Note 24)	10	25	10	25	10	25	ns	
t _{CS}	RAS hold time after CAS low	20		20		25		ns	

Note 24: t_{CP(max)} is specified as a reference point only. If t_{CP(max)} ≤ t_{CP}, access time is assumed by t_{CAC}.**CAS before RAS Refresh Cycle (Note 25)**

Symbol	Parameter	Limits						Unit	
		M5M41000B-7		M5M41000B-8		M5M41000B-10			
		Min	Max	Min	Max	Min	Max		
t _{CSR}	CAS setup time for CAS before RAS refresh	10		10		10		ns	
t _{CHSR}	CAS hold time for CAS before RAS refresh	15		15		20		ns	
t _{RPC}	Precharge to CAS active time	0		0		0		ns	

Note 25: Eight or more CAS before RAS cycles instead of eight RAS cycles are necessary for proper operation of CAS before RAS refresh mode.

M5M41000BP, J, L, VP, RW-7, -8, -10**FAST PAGE MODE 1048576-BIT(1048576-WORD BY 1-BIT)DYNAMIC RAM****Timing Diagrams (Note 26)****Read Cycle**

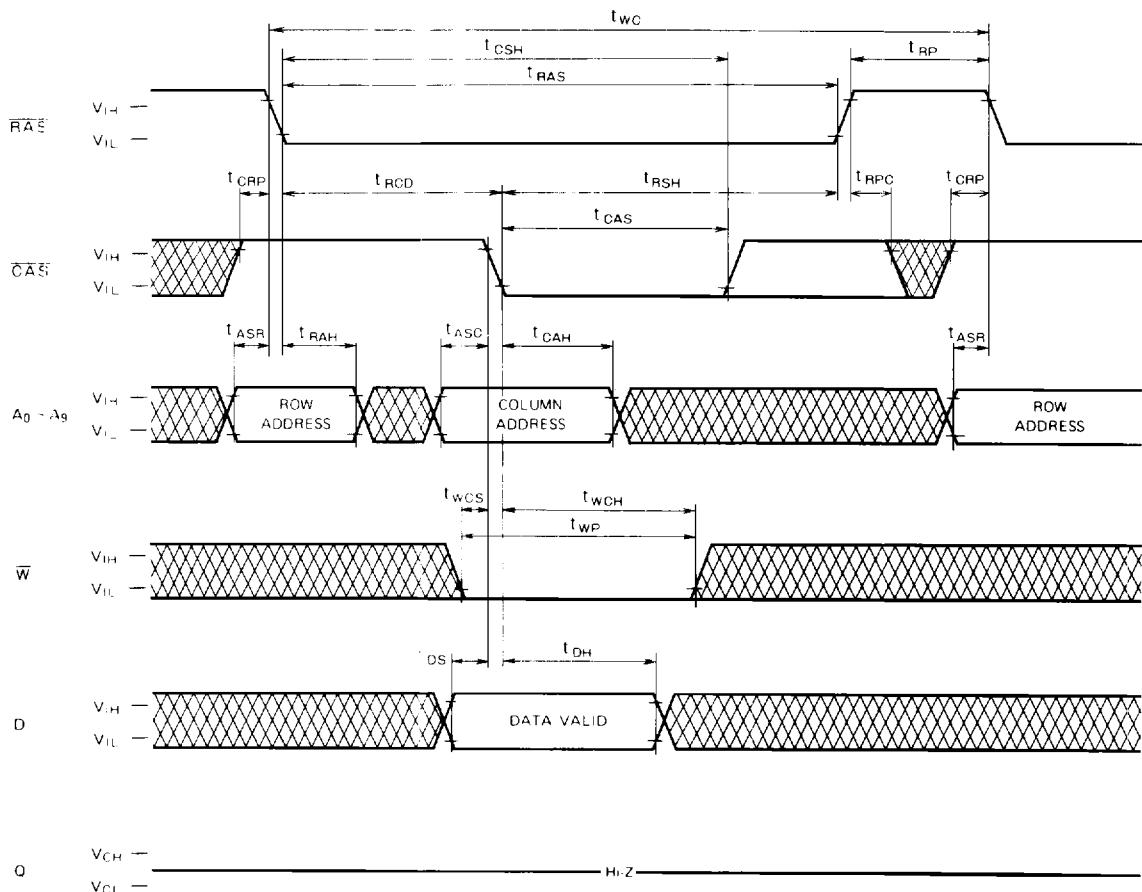
Note 26

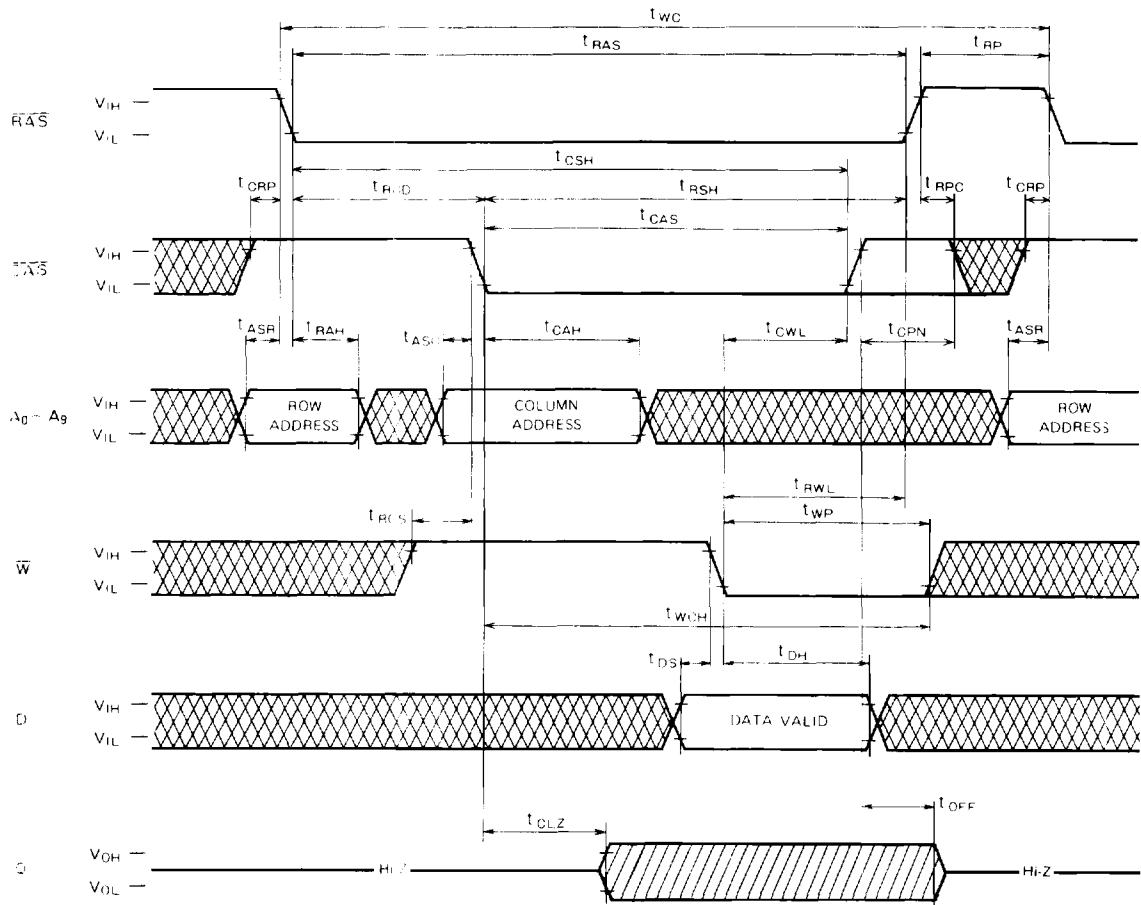


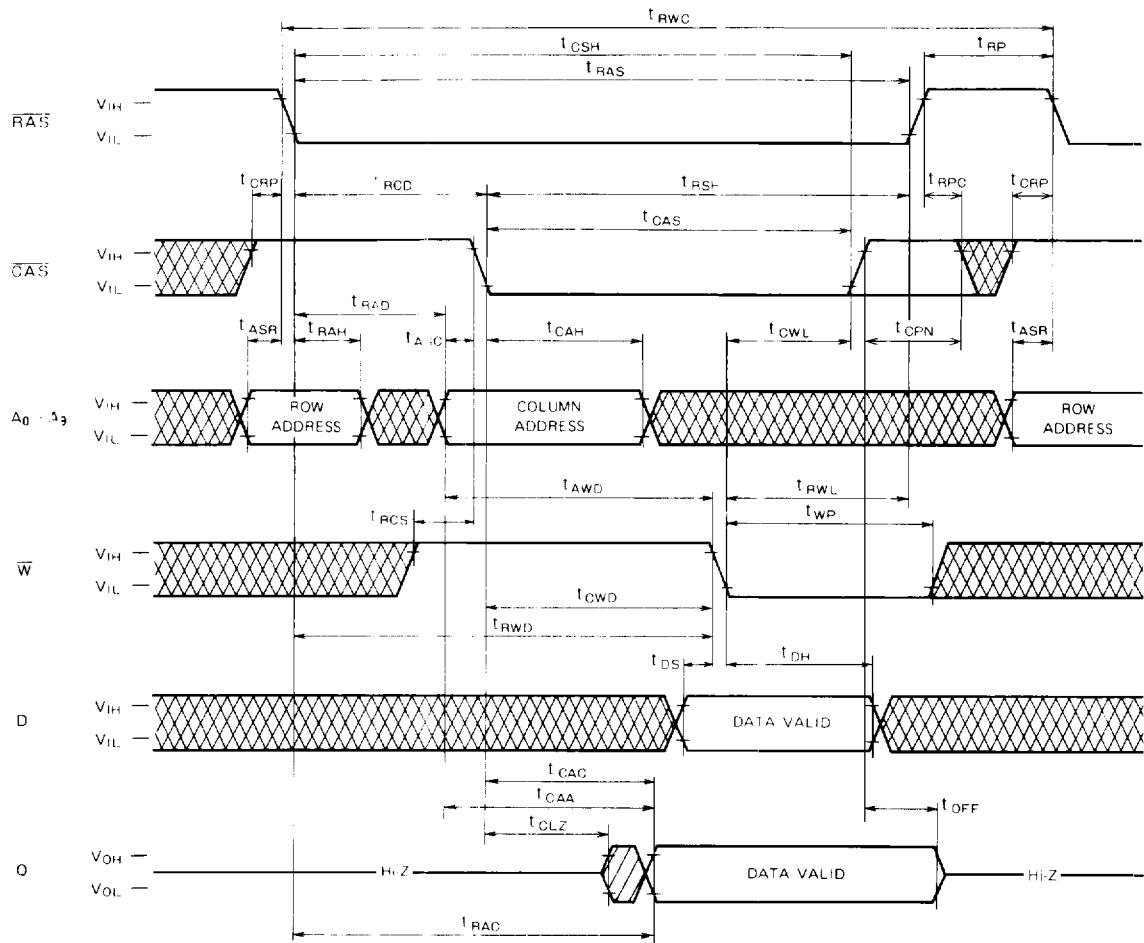
Indicates the don't care input.
 $V_{IH(min)} \leq V_{IN} \leq V_{IH(max)}$ or $V_{IL(min)} \leq V_{IN} \leq V_{IL(max)}$

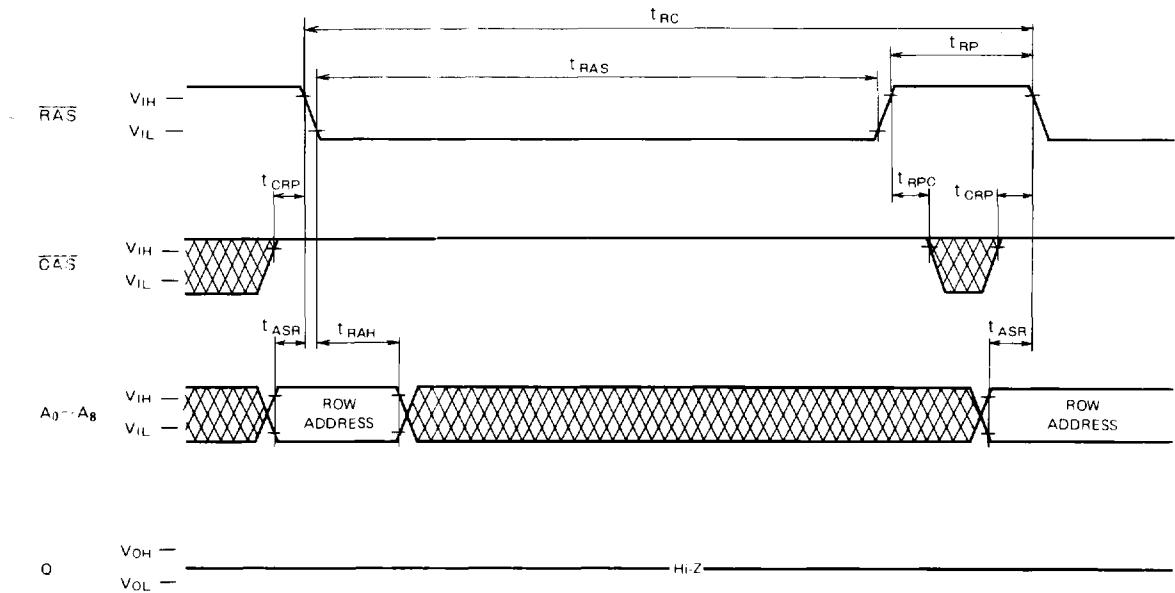


Indicates the invalid output.

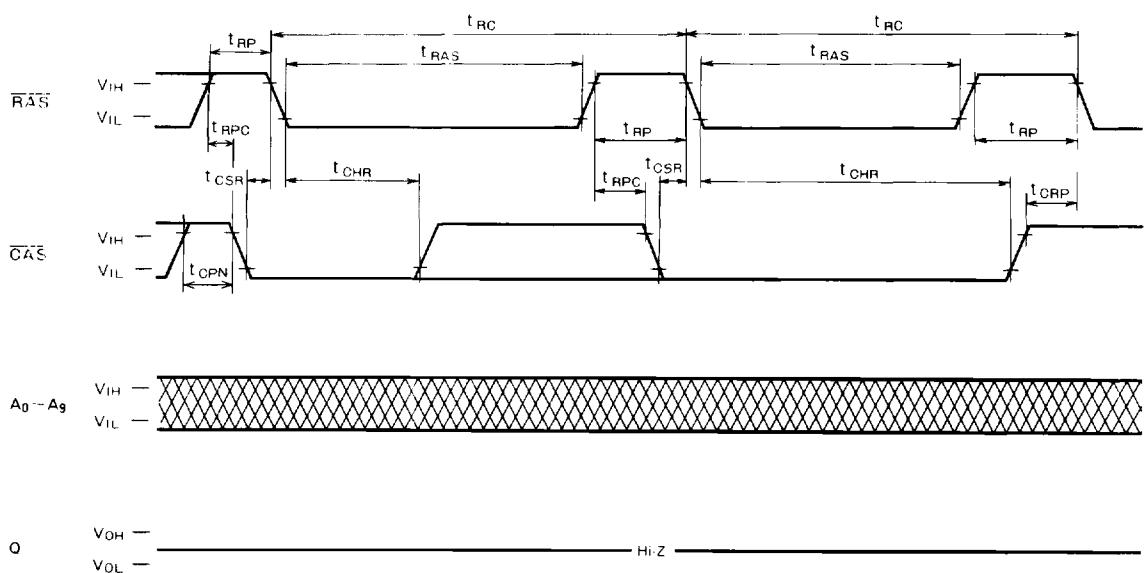
M5M41000BP, J, L, VP, RW-7, -8, -10**FAST PAGE MODE 1048576-BIT(1048576-WORD BY 1-BIT)DYNAMIC RAM****Write Cycle (Early write)**

FAST PAGE MODE 1048576-BIT(1048576-WORD BY 1-BIT) DYNAMIC RAM**Write Cycle (Delayed Write)**

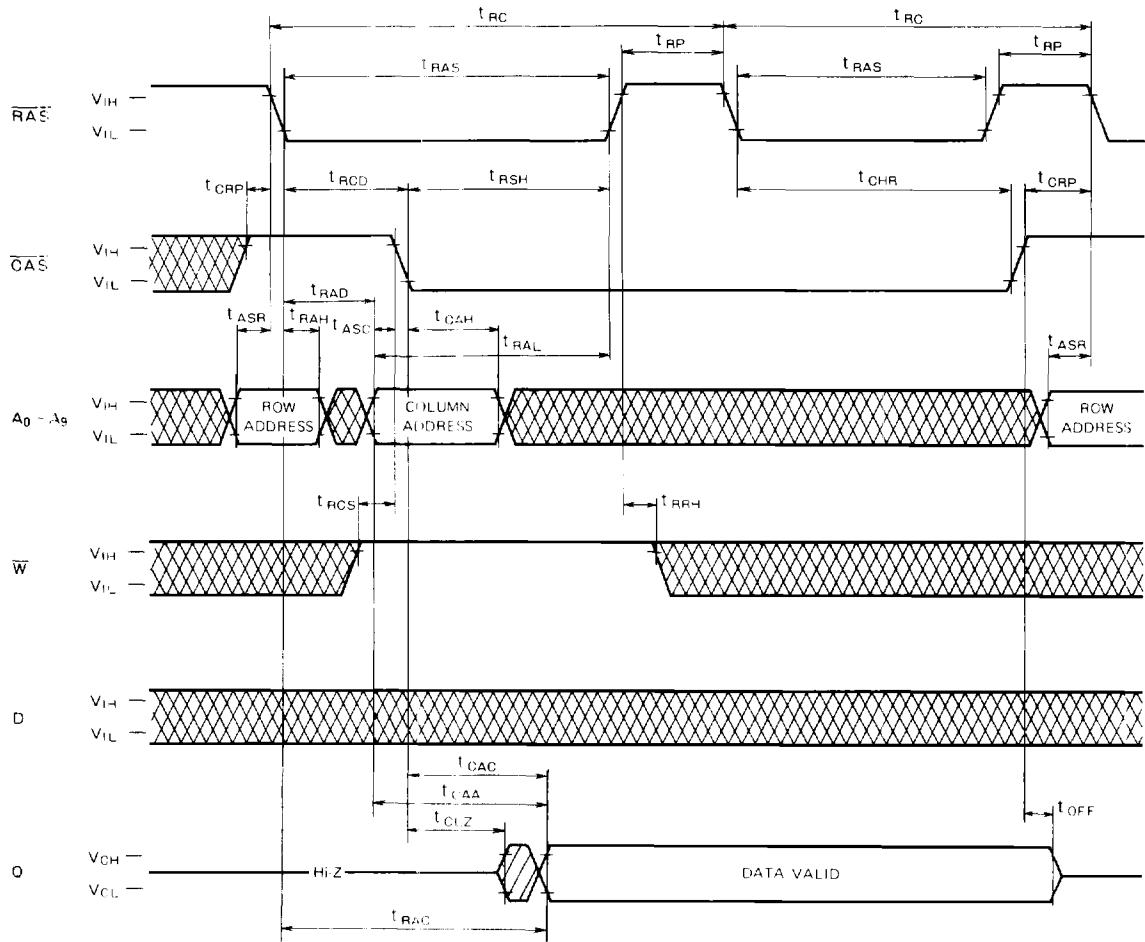
M5M41000BP, J, L, VP, RW-7, -8, -10**FAST PAGE MODE 1048576-BIT(1048576-WORD BY 1-BIT)DYNAMIC RAM****Read-Write, Read-Modify-Write Cycle**

M5M41000BP, J, L, VP, RV-7, -8, -10**FAST PAGE MODE 1048576-BIT(1048576-WORD BY 1-BIT)DYNAMIC RAM****RAS-only Refresh Cycle (Note 27)**

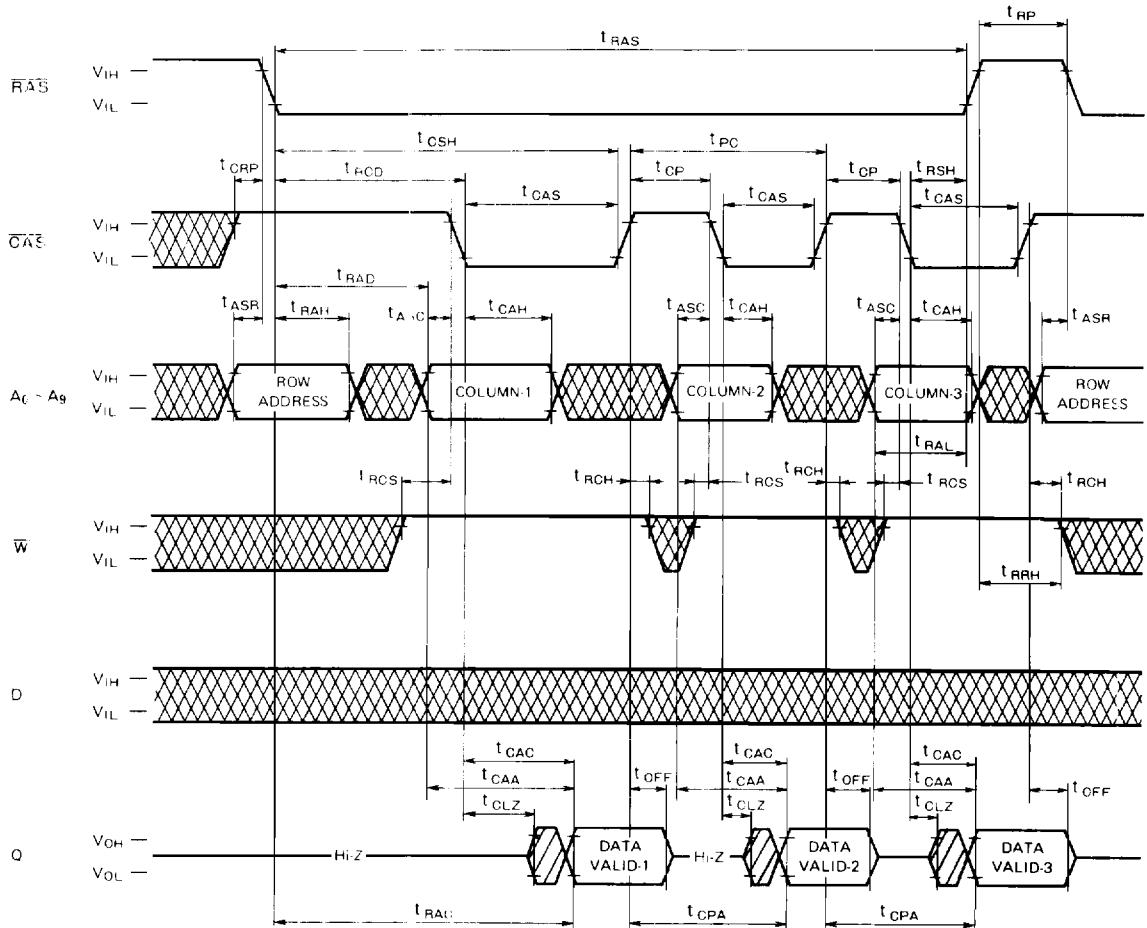
Note 27: \overline{W}, D = don't care, A_9 may be V_{IH} or V_{IL}

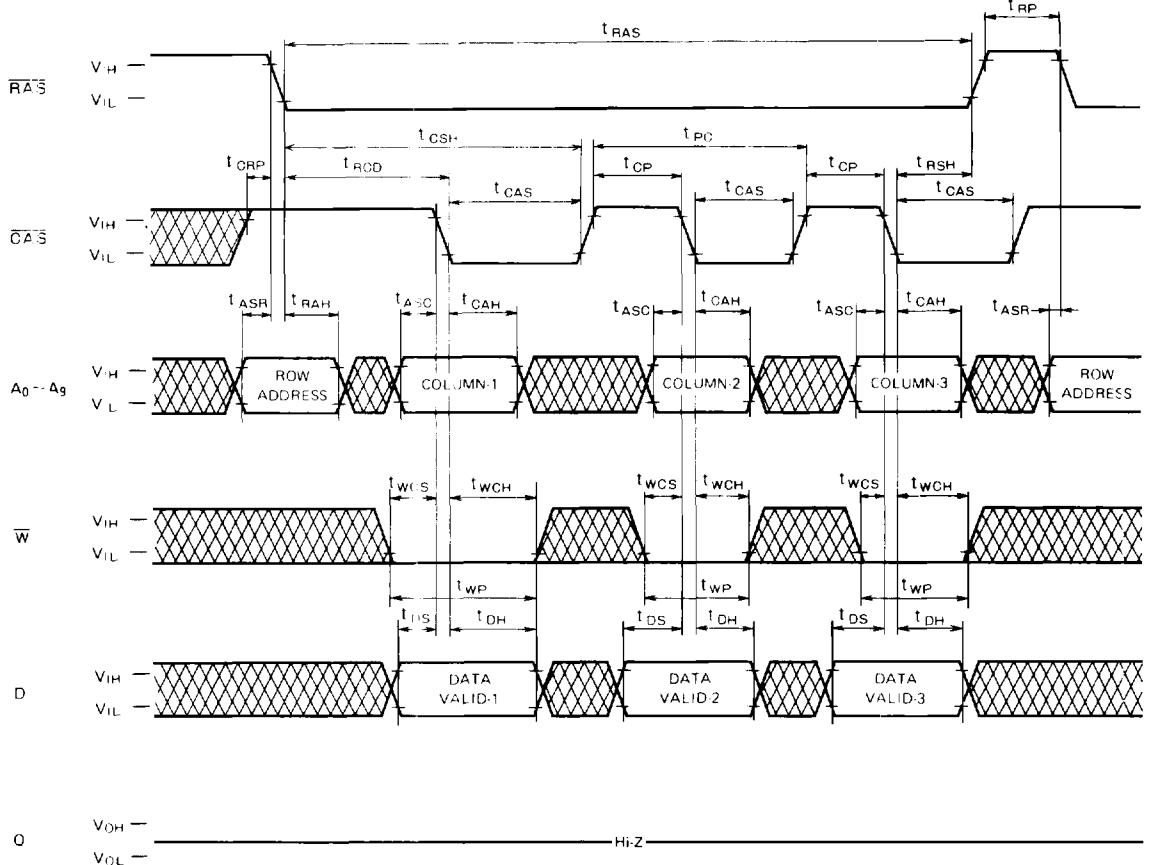
CAS before RAS Refresh Cycle (Note 28)

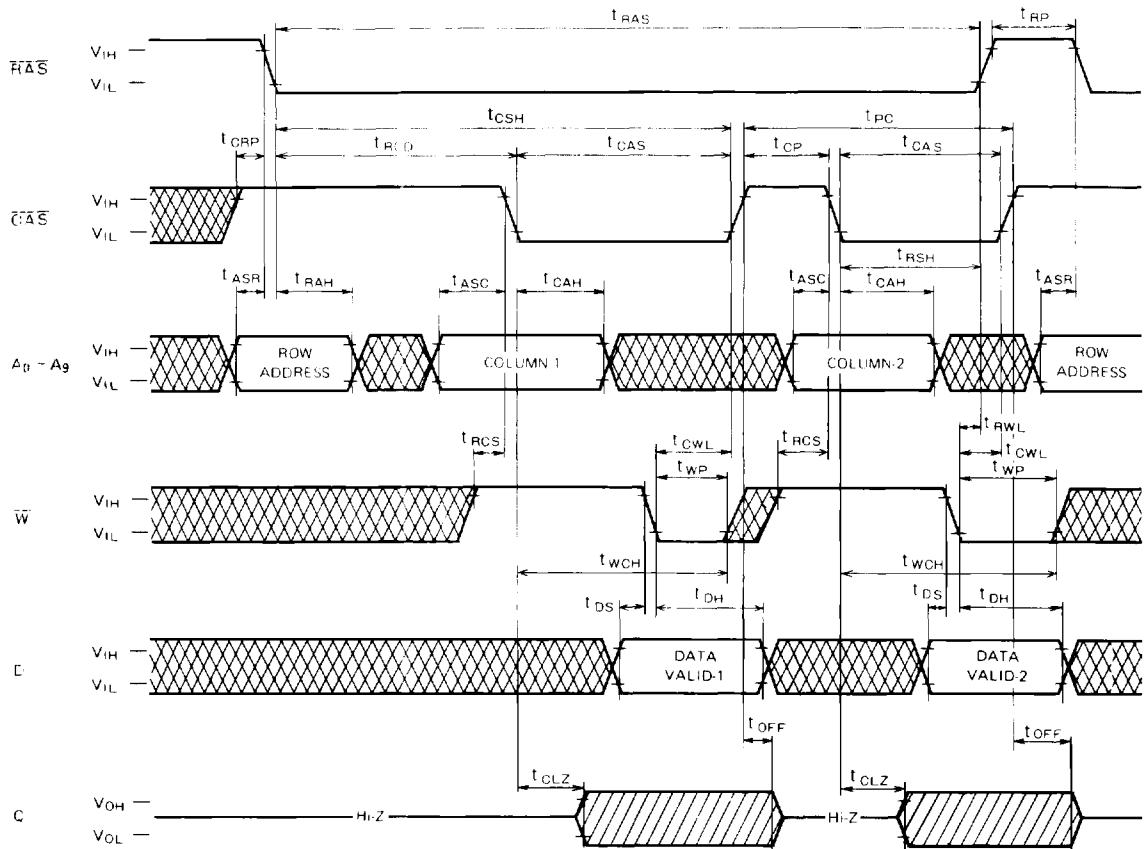
Note 28: \overline{W}, D = don't care

M5M41000BP, J, L, VP, RW-7, -8, -10**FAST PAGE MODE 1048576-BIT(1048576-WORD BY 1-BIT)DYNAMIC RAM****Hidden Refresh Cycle (Read) (Note 29)**

Note 29: Early write, delayed write, read-write or read-modify-write cycle is applicable instead of read cycle
 Timing requirements and output state are the same as that of each cycle shown before.

FAST PAGE MODE 1048576-BIT(1048576-WORD BY 1-BIT)DYNAMIC RAM**Fast-Page-Mode Read Cycle**

M5M41000BP, J, L, VP, RV-7, -8, -10**FAST PAGE MODE 1048576-BIT(1048576-WORD BY 1-BIT)DYNAMIC RAM****Fast-Page-Mode Write Cycle (Early Write)**

M5M41000BP, J, L, VP, RV-7, -8, -10**FAST PAGE MODE 1048576-BIT(1048576-WORD BY 1-BIT)DYNAMIC RAM****Fast-Page-Mode Write Cycle (Delayed Write)**

M5M41000BP, J, L, VP, RV-7, -8, -10**FAST PAGE MODE 1048576-BIT(1048576-WORD BY 1-BIT)DYNAMIC RAM****Fast-Page-Mode Read-Write, Read-Modify-Write Cycle**